

Title (en)
A chip arrangement and a method for manufacturing a chip arrangement

Title (de)
Chipanordnung und Verfahren zur Herstellung einer Chipanordnung

Title (fr)
Ensemble de puces et procédé de fabrication d'un tel ensemble

Publication
EP 2779237 A3 20180103 (EN)

Application
EP 14158271 A 20140307

Priority
US 201313802843 A 20130314

Abstract (en)
[origin: EP2779237A2] A chip arrangement may include: a first semiconductor chip having a first side and a second side opposite the first side; a second semiconductor chip having a first side and a second side opposite the first side, the second semiconductor chip disposed at the first side of the first semiconductor chip and electrically coupled to the first semiconductor chip, the first side of the second semiconductor chip facing the first side of the first semiconductor chip; an encapsulation layer at least partially encapsulating the first semiconductor chip and the second semiconductor chip, the encapsulation layer having a first side and a second side opposite the first side, the second side facing in a same direction as the second side of the second semiconductor chip; and an interconnect structure disposed at least partially within the encapsulation layer and electrically coupled to at least one of the first and second semiconductor chips, wherein the interconnect structure may extend to the second side of the encapsulation layer.

IPC 8 full level
H01L 21/56 (2006.01); **H01L 21/98** (2006.01); **H01L 23/31** (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP US)
H01L 21/4846 (2013.01 - US); **H01L 21/56** (2013.01 - US); **H01L 21/563** (2013.01 - EP US); **H01L 21/565** (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 23/49816** (2013.01 - EP US); **H01L 23/49838** (2013.01 - US); **H01L 23/5386** (2013.01 - US); **H01L 23/5389** (2013.01 - EP US); **H01L 24/19** (2013.01 - EP US); **H01L 24/96** (2013.01 - EP US); **H01L 25/0657** (2013.01 - EP US); **H01L 25/50** (2013.01 - EP US); **H01L 21/568** (2013.01 - EP US); **H01L 23/3114** (2013.01 - EP US); **H01L 23/525** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/04105** (2013.01 - EP US); **H01L 2224/12105** (2013.01 - EP US); **H01L 2224/16145** (2013.01 - EP US); **H01L 2224/16225** (2013.01 - EP US); **H01L 2224/1703** (2013.01 - EP US); **H01L 2224/2518** (2013.01 - EP); **H01L 2224/32145** (2013.01 - EP); **H01L 2224/73204** (2013.01 - EP); **H01L 2224/73209** (2013.01 - EP US); **H01L 2224/92125** (2013.01 - EP); **H01L 2224/94** (2013.01 - EP US); **H01L 2224/97** (2013.01 - EP US); **H01L 2225/06513** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - US); **H01L 2225/06548** (2013.01 - US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2924/1461** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/15321** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/18161** (2013.01 - EP US); **H01L 2924/18162** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H01L 2924/19042** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H01L 2924/19104** (2013.01 - EP US)

Citation (search report)
• [X] US 2011285007 A1 20111124 - CHI HEEJO [KR], et al
• [XA] US 2013037950 A1 20130214 - YU CHUN HUI [TW], et al
• [A] EP 2178113 A1 20100421 - NXP BV [NL]

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

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